



Material Content Data Sheet



Sales Product Name	SAK-XC164CS-32F40F BB-A			Issued		19. September 2019		
MA#	MA001506566							
Package	PG-TQFP-100-5			Weight*		718.16 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	33.010	4.60	4.60	45965	45965
leadframe	non noble metal	magnesium	7439-95-4	0.301	0.04		419	
	inorganic material	silicon	7440-21-3	1.305	0.18		1817	
	non noble metal	nickel	7440-02-0	6.023	0.84		8387	
	non noble metal	copper	7440-50-8	193.148	26.90	27.96	268950	279573
wire	noble metal	gold	7440-57-5	2.953	0.41	0.41	4112	4112
encapsulation	organic material	carbon black	1333-86-4	2.315	0.32		3223	
	plastics	epoxy resin	-	62.498	8.70		87026	
	inorganic material	silicondioxide	60676-86-0	398.138	55.44	64.46	554389	644638
leadfinish	non noble metal	tin	7440-31-5	6.211	0.86	0.86	8649	8649
plating	noble metal	silver	7440-22-4	6.180	0.86	0.86	8606	8606
glue	plastics	epoxy resin	-	1.215	0.17		1691	
	noble metal	silver	7440-22-4	4.859	0.68	0.85	6766	8457
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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